

2009 International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP)

The 10th Anniversary of International Conference on Electronic Packaging Technology(ICEPT)
 August 10 ~13 , 2009, Beijing, China

On behalf of the China Electronic Packaging Society, Chinese Institute of Electronics (CIE-CEPS), it is my great pleasure to invite you to submit abstracts and attend 2009 International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP 2009), to be held in Beijing, China from August 10 to 13, 2009.

Hosted by CIE-CEPS, the International Conference on Electronic Packaging Technology (ICEPT) will celebrate her 10th anniversary this year. In 1994, initiated by Tsinghua University, Fudan University, China Institute of Electronic Science, the 13th and 58th Research Institutes of CETC and others, the first International Symposium on Microelectronic Package & PCB Technology was held, which was the initiation of the ICEPT. This conference was held for nine times by 2008. They were organized in rotation by the leading universities in China, among which Tsinghua University held 3 times, and Fudan University, Harbin Institute of Technology, Huazhong University of Science & Technology, Shanghai Jiaotong University organized another 6 times. This conference has provided a great technical platform for international and domestic experts, scholars, and researchers from academia and industries to exchange their ideas on the development of electronic packaging. It was highly appreciated by China Institute of Electronics, China Association of Science, and the former Ministry of Information Industry, and greatly supported by IEEE-CPMT and IMAPS. In 2008, the ICEPT and the International Symposium on High Density Packaging (HDP), organized by Shanghai University, were merged as the International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP). It was successfully held in Shanghai, China and received great appreciation and supports from both academia and industries.

ICEPT-HDP 2009 is a 4-day event, to be organized by Tsinghua University. The conference will feature short courses, conference keynotes, special forums and technical sessions to cover the technological developments in all the areas of electronics packaging. In conjunction with the conference, the ICEPT 10th Anniversary Celebration will be held. We sincerely invite all the leaders, experts, and peers who have been supporting this conference to come and meet in Beijing.

Keyun BI , General Chair

Vice Director General of Standing Committee of China Institute of Electronics

President of Packaging Branch, China Semiconductor Industrial Association

President of China Electronic Packaging Society



IMPORTANT DATES

- ◆ April 27, 2009 – Submission of Abstract
- ◆ May 08, 2009 – Notification of Acceptance
- ◆ July 13 , 2009 – Submission of Manuscript

SUBMISSION OF ABSTRACT/PAPER

Abstracts are solicited to describe original and unpublished work. The abstract should be approx.


500 words and contains a clear statement of the background, methodology, results, conclusions and important references of the work. All abstracts must be in English and should be submitted using the format provided in the attached word file through the email: icept2009@tsinghua.edu.cn or icept2009@grand-tech.net.cn.

The abstracts must be received by **April 27, 2009**. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance by **May 08, 2009**. The final manuscript for publication in the conference proceedings is due by **July 13, 2009**. Selected papers will be recommended for publication in IEEE/CPMT journals.


CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components and software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may email icept2009@tsinghua.edu.cn or icept2009@grand-tech.net.cn for details.


Download Call For Papers:

 http://www.eeworld.com.cn/zhuanti/icept2009/ICEPT-HDP%202009_CFP_En-20090406.pdf

Download ICEPT-HDP 2009_Format for Abstract Submission:

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News: 2009 Spring PCB Technology & Information Conference March 17 ~18 Shanghai, China

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